

## 8. Specifications

Backplane (IMB) Supply	20 Vdc to 32 Vdc
Field Supply	N/A
Power Dissipation	10 W
Module Location	T8100, T8300 I/O Module Slot
Isolation	50 V Basic Insulation, Module to Backplane Supply, Module to Diagnostic Serial Port  250 V Basic Insulation, Module to Rear Serial Ports, Module to Ethernet Ports, Serial Ports to Ethernet Ports, Between Serial Ports, Between Ethernet Ports
Fusing	Not User Serviceable
Ports	2 Rear Serial Ports, RS-232/422/485 2 Rear Serial Ports, RS-422/485 2 Ethernet Ports, 10/100BaseT 1 Diagnostics Serial Port, RS-232
Baud Rates	1200 baud to 115200 baud
Communications Protocols (See 3.1 Supported Protocols for further details)	Modbus RTU Open Modbus TCP Trusted Peer to Peer Trusted Enhanced Peer to Peer ICS2000 CP2000
SOE Buffer	4000 Events
Operating Temperature	0 °C to +60 °C (+32 °F to +140 °F)
Storage Temperature	-25 °C to +70 °C (-13 °F to +158 °F)
Relative Humidity - Operating and Storage	10 % – 95 %, non-condensing